

Wide-Input Sensorless CC/CV Step-Down DC/DC Converter

FEATURES

- Up to 40V Input Voltage
- Up to 2A output current
- Output Voltage up to 12V
- Patent Pending Active CC Sensorless Constant Current Control
 - Integrated Current Control Improves Efficiency, Lowers Cost, and Reduces Component Count
- Resistor Programmable
 - Current Limit from 750mA to 2A
 - Patented Cable Compensation from 0Ω to 0.5Ω
- $\pm 7.5\%$ CC Accuracy
 - Compensation of Input /Output Voltage Change
 - Temperature Compensation
 - Independent of inductance and Inductor DCR
- 2% Feedback Voltage Accuracy
- Up to 93% Efficiency
- 210kHz Switching Frequency Eases EMI Design
- Advanced Feature Set
 - Integrated Soft Start
 - Thermal Shutdown
 - Secondary Cycle-by-Cycle Current Limit
 - Protection Against Shorted ISET Pin
- SOP-8EP Package

APPLICATIONS

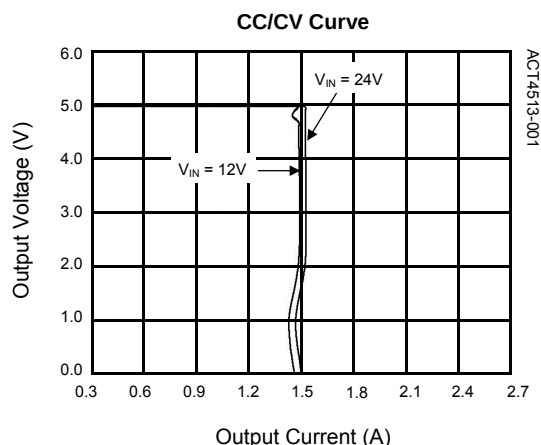
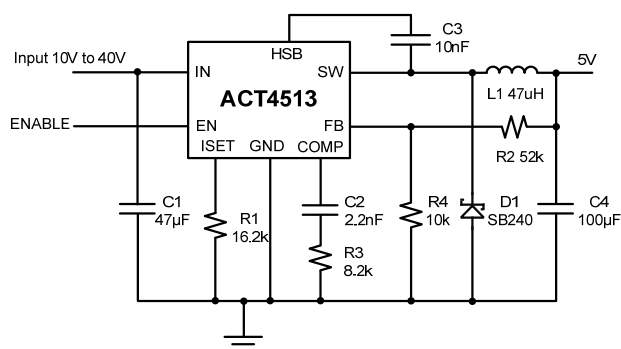
- Car Charger/ Adaptor
- Rechargeable Portable Devices
- General-Purpose CC/CV Supply

GENERAL DESCRIPTION

ACT4513 is a wide input voltage, high efficiency Active CC step-down DC/DC converter that operates in either CV (Constant Output Voltage) mode or CC (Constant Output Current) mode. ACT4513 provides up to 2A output current at 210kHz switching frequency.

Active CC is a patent-pending control scheme to achieve highest accuracy sensorless constant current control. Active CC eliminates the expensive, high accuracy current sense resistor, making it ideal for battery charging applications and adaptors with accurate current limit. The ACT4513 achieves higher efficiency than traditional constant current switching regulators by eliminating its associated power loss.

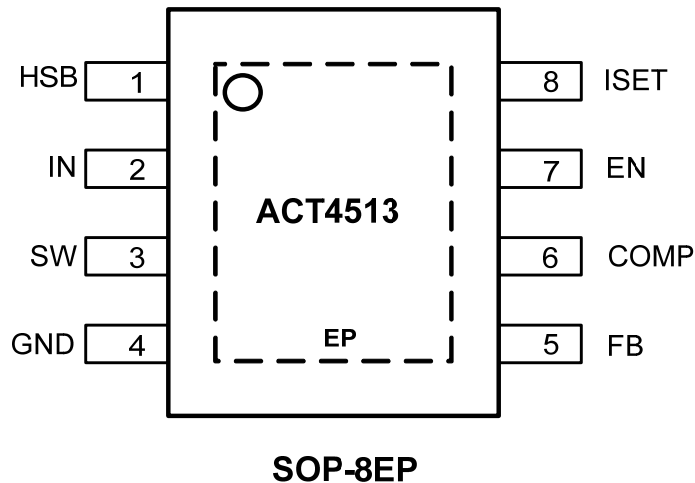
Protection features include cycle-by-cycle current limit, thermal shutdown, and frequency foldback at short circuit. The devices are available in a SOP-8EP package and require very few external devices for operation.



ORDERING INFORMATION

PART NUMBER	OPERATION TEMPERATURE RANGE	PACKAGE	PINS	PACKING
ACT4513YH-T	-40°C to 85°C	SOP-8EP	8	TAPE & REEL

PIN CONFIGURATION



PIN DESCRIPTIONS

PIN	NAME	DESCRIPTION
1	HSB	High Side Bias Pin. This provides power to the internal high-side MOSFET gate driver. Connect a 10nF capacitor from HSB pin to SW pin.
2	IN	Power Supply Input. Bypass this pin with a 10μF ceramic capacitor to GND, placed as close to the IC as possible.
3	SW	Power Switching Output to External Inductor.
4	GND	Ground. Connect this pin to a large PCB copper area for best heat dissipation. Return FB, COMP, and ISET to this GND, and connect this GND to power GND at a single point for best noise immunity.
5	FB	Feedback Input. The voltage at this pin is regulated to 0.808V. Connect to the resistor divider between output and GND to set the output voltage.
6	COMP	Error Amplifier Output. This pin is used to compensate the converter.
7	EN	Enable Input. EN is pulled up to 5V with a 4μA current, and contains a precise 0.8V logic threshold. Drive this pin to a logic-high or leave unconnected to enable the IC. Drive to a logic-low to disable the IC and enter shutdown mode.
8	ISET	Output Current Setting Pin. Connect a resistor from ISET to GND to program the output current.
	Exposed Pad	Heat Dissipation Pad. Connect this exposed pad to large ground copper area with copper and vias.

ABSOLUTE MAXIMUM RATINGS^①

PARAMETER	VALUE	UNIT
IN to GND	-0.3 to 40	V
SW to GND	-1 to $V_{IN} + 1$	V
HSB to GND	$V_{SW} - 0.3$ to $V_{SW} + 7$	V
FB, EN, ISET, COMP to GND	-0.3 to + 6	V
Junction to Ambient Thermal Resistance	50	°C/W
Operating Junction Temperature	-40 to 135	°C
Storage Junction Temperature	-55 to 150	°C
Lead Temperature (Soldering 10 sec.)	300	°C

①: Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

($V_{IN} = 14V$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input Voltage		10		40	V
V_{IN} UVLO Turn-On Voltage	Input Voltage Rising	9.05	9.35	9.65	V
V_{IN} UVLO Hysteresis	Input Voltage Falling		1.1		V
Standby Supply Current	$V_{EN} = 3V$, $V_{FB} = 1V$		1.0		mA
	$V_{EN} = 3V$, $V_{OUT} = 5V$, No load		2.5		mA
Shutdown Supply Current	$V_{EN} = 0V$		75	100	μA
Feedback Voltage		792	808	824	mV
Internal Soft-Start Time			400		μs
Error Amplifier Transconductance	$V_{FB} = V_{COMP} = 0.8V$, $\Delta I_{COMP} = \pm 10\mu A$		650		$\mu A/V$
Error Amplifier DC Gain			4000		V/V
Switching Frequency	$V_{FB} = 0.808V$	190	210	240	kHz
Foldback Switching Frequency	$V_{FB} = 0V$		30		kHz
Maximum Duty Cycle			88		%
Minimum On-Time			200		ns
COMP to Current Limit Transconductance	$V_{COMP} = 1.2V$		3.4		A/V
Secondary Cycle-by-Cycle Current Limit	Duty = 50%		3.2		A
Slope Compensation	Duty = D_{MAX}		0.75		A
ISET Voltage			1		V
ISET to IOUT DC Room Temp Current Gain	IOUT / ISET		25000		A/A
CC Controller DC Accuracy	$R_{ISET} = 19.6k\Omega$, $V_{IN} = 10V - 30V$	1274	1300	1326	mA
EN Threshold Voltage	EN Pin Rising	0.75	0.8	0.85	V
EN Hysteresis	EN Pin Falling		80		mV
EN Internal Pull-up Current			4		μA
High-Side Switch ON-Resistance			0.22		Ω
SW Off Leakage Current	$V_{EN} = V_{SW} = 0V$		1	10	μA
Thermal Shutdown Temperature	Temperature Rising		155		$^\circ C$

The block diagram illustrates a power supply control system. The input voltage is labeled **IN**. The output voltage is labeled **PVIN**. The output current is labeled **HSB**. The output voltage is also labeled **SW**. The system includes a **BANDGAP, REGULATOR, & SHUTDOWN CONTROL** block, which provides a reference voltage $V_{REF} = 0.808V$. This reference voltage is compared with the output voltage **PVIN** in a summing junction (Σ). The error signal is then processed by a **PWM CONTROLLER** block, which generates a pulse-width modulated signal. This signal is used to drive a power MOSFET (represented by a triangle and a MOSFET symbol) and a power diode (represented by a circle and a diode symbol). The MOSFET and diode are connected to the output voltage **SW**. The output voltage **SW** is also fed back to the **BANDGAP, REGULATOR, & SHUTDOWN CONTROL** block and the summing junction. The output current **HSB** is fed back to the **CC CONTROL** block, which provides a current feedback signal to the summing junction. The output voltage **SW** is also fed back to the **COMP** block, which provides a compensation signal to the **PWM CONTROLLER**. The output current **HSB** is also fed back to the **ISET** block, which provides a current setpoint signal to the **CC CONTROL** block. The output voltage **SW** is also fed back to the **EN** block, which provides an enable signal to the **BANDGAP, REGULATOR, & SHUTDOWN CONTROL** block.

The ACT4513 disables switching when its junction temperature exceeds 155°C and resumes when the temperature has dropped by 20°C.

APPLICATIONS INFORMATION

Output Voltage Setting

Figure 1:

Output Voltage Setting

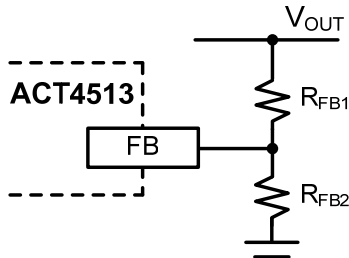


Figure 1 shows the connections for setting the output voltage. Select the proper ratio of the two feedback resistors R_{FB1} and R_{FB2} based on the output voltage. Typically, use $R_{FB2} \approx 10k\Omega$ and determine R_{FB1} from the following equation:

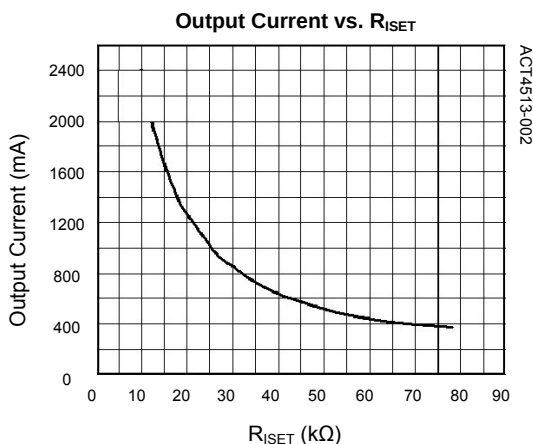
$$R_{FB1} = R_{FB2} \left(\frac{V_{OUT}}{0.808V} - 1 \right) \quad (1)$$

CC Current Setting

ACT4513 constant current value is set by a resistor connected between the ISET pin and GND. The CC output current is linearly proportional to the current flowing out of the ISET pin. The voltage at ISET is roughly 1V and the current gain from ISET to output is roughly 25000 (25mA/1μA). To determine the proper resistor for a desired current, please refer to Figure 2 below.

Figure 2:

Curve for Programming Output CC Current

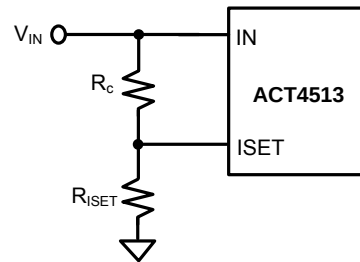


CC Current Line Compensation

When operating at constant current mode, the current limit increase slightly with input voltage. For wide input voltage applications, a resistor R_C is added to compensate line change and keep output high CC accuracy, as shown in Figure 3.

Figure 3:

Output Line Compensation



Inductor Selection

The inductor maintains a continuous current to the output load. This inductor current has a ripple that is dependent on the inductance value:

Higher inductance reduces the peak-to-peak ripple current. The trade off for high inductance value is the increase in inductor core size and series resistance, and the reduction in current handling capability. In general, select an inductance value L based on ripple current requirement:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} f_{SW} I_{LOADMAX} K_{RIPPLE}} \quad (2)$$

where V_{IN} is the input voltage, V_{OUT} is the output voltage, f_{SW} is the switching frequency, $I_{LOADMAX}$ is the maximum load current, and K_{RIPPLE} is the ripple factor. Typically, choose $K_{RIPPLE} = 30\%$ to correspond to the peak-to-peak ripple current being 30% of the maximum load current.

With a selected inductor value the peak-to-peak inductor current is estimated as:

$$I_{LPK-PK} = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{L \times V_{IN} \times f_{SW}} \quad (3)$$

The peak inductor current is estimated as:

$$I_{LPK} = I_{LOADMAX} + \frac{1}{2} I_{LPK-PK} \quad (4)$$

APPLICATIONS INFORMATION CONT'D

The selected inductor should not saturate at I_{LPK} .
 The maximum output current is calculated as:

$$I_{OUTMAX} = I_{LIM} - \frac{1}{2} I_{LPK-PK} \quad (5)$$

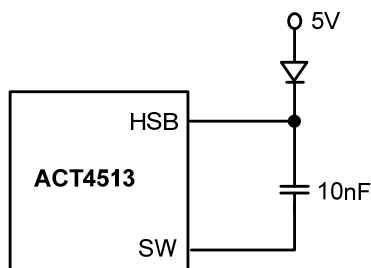
I_{LIM} is the internal current limit, which is typically 3.2A, as shown in Electrical Characteristics Table.

External High Voltage Bias Diode

It is recommended that an external High Voltage Bias diode be added when the system has a 5V fixed input or the power supply generates a 5V output. This helps improve the efficiency of the regulator. The High Voltage Bias diode can be a low cost one such as IN4148 or BAT54.

Figure 4:

External High Voltage Bias Diode



This diode is also recommended for high duty cycle operation and high output voltage applications.

Input Capacitor

The input capacitor needs to be carefully selected to maintain sufficiently low ripple at the supply input of the converter. A low ESR capacitor is highly recommended. Since large current flows in and out of this capacitor during switching, its ESR also affects efficiency.

The input capacitance needs to be higher than 10μF. The best choice is the ceramic type, however, low ESR tantalum or electrolytic types may also be used provided that the RMS ripple current rating is higher than 50% of the output current. The input capacitor should be placed close to the IN and GND pins of the IC, with the shortest traces possible. In the case of tantalum or electrolytic types, they can be further away if a small parallel 0.1μF ceramic capacitor is placed right next to the IC.

Output Capacitor

The output capacitor also needs to have low ESR to keep low output voltage ripple. The output ripple voltage is:

$$V_{RIPPLE} = I_{OUTMAX} K_{RIPPLE} R_{ESR} + \frac{V_{IN}}{28 \times f_{SW}^2 L C_{OUT}} \quad (6)$$

Where I_{OUTMAX} is the maximum output current, K_{RIPPLE} is the ripple factor, R_{ESR} is the ESR of the output capacitor, f_{SW} is the switching frequency, L is the inductor value, and C_{OUT} is the output capacitance. In the case of ceramic output capacitors, R_{ESR} is very small and does not contribute to the ripple. Therefore, a lower capacitance value can be used for ceramic type. In the case of tantalum or electrolytic capacitors, the ripple is dominated by R_{ESR} multiplied by the ripple current. In that case, the output capacitor is chosen to have sufficiently low ESR.

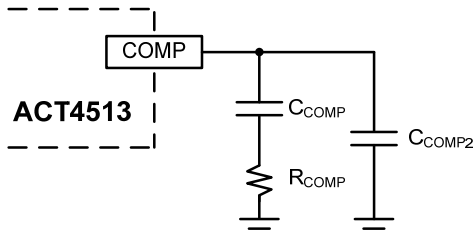
For ceramic output capacitor, typically choose a capacitance of about 22μF. For tantalum or electrolytic capacitors, choose a capacitor with less than 50mΩ ESR.

Rectifier Diode

Use a Schottky diode as the rectifier to conduct current when the High-Side Power Switch is off. The Schottky diode must have current rating higher than the maximum output current and a reverse voltage rating higher than the maximum input voltage.

STABILITY COMPENSATION

Figure 5:
Stability Compensation



①: C_{COMP2} is needed only for high ESR output capacitor

The feedback loop of the IC is stabilized by the components at the COMP pin, as shown in Figure 3. The DC loop gain of the system is determined by the following equation:

$$A_{VDC} = \frac{0.808V}{I_{OUT}} A_{VEA} G_{COMP} \quad (7)$$

The dominant pole P1 is due to C_{COMP}:

$$f_{P1} = \frac{G_{EA}}{2\pi A_{VEA} C_{COMP}} \quad (8)$$

The second pole P2 is the output pole:

$$f_{P2} = \frac{I_{OUT}}{2\pi V_{OUT} C_{OUT}} \quad (9)$$

The first zero Z1 is due to R_{COMP} and C_{COMP}:

$$f_{Z1} = \frac{1}{2\pi R_{COMP} C_{COMP}} \quad (10)$$

And finally, the third pole is due to R_{COMP} and C_{COMP2} (if C_{COMP2} is used):

$$f_{P3} = \frac{1}{2\pi R_{COMP} C_{COMP2}} \quad (11)$$

The following steps should be used to compensate the IC:

STEP 1. Set the cross over frequency at 1/10 of the switching frequency via R_{COMP}:

$$R_{COMP} = \frac{2\pi V_{OUT} C_{OUT} f_{SW}}{10 G_{EA} G_{COMP} \times 0.808V} = 2.75 \times 10^8 V_{OUT} C_{OUT} \quad (\Omega) \quad (12)$$

STEP 2. Set the zero f_{Z1} at 1/4 of the cross over frequency. If R_{COMP} is less than 15kΩ, the equation for C_{COMP} is:

$$C_{COMP} = \frac{1.8 \times 10^{-5}}{R_{COMP}} \quad (F) \quad (13)$$

If R_{COMP} is limited to 15kΩ, then the actual cross over frequency is 3.4 / (V_{OUT}C_{OUT}). Therefore:

$$C_{COMP} = 1.2 \times 10^{-5} V_{OUT} C_{OUT} \quad (F) \quad (14)$$

STEP 3. If the output capacitor's ESR is high enough to cause a zero at lower than 4 times the cross over frequency, an additional compensation capacitor C_{COMP2} is required. The condition for using C_{COMP2} is:

$$R_{ESRCOUT} \geq \text{Min} \left(\frac{1.1 \times 10^{-6}}{C_{OUT}}, 0.012 \times V_{OUT} \right) \quad (\Omega) \quad (15)$$

And the proper value for C_{COMP2} is:

$$C_{COMP2} = \frac{C_{OUT} R_{ESRCOUT}}{R_{COMP}} \quad (16)$$

Though C_{COMP2} is unnecessary when the output capacitor has sufficiently low ESR, a small value C_{COMP2} such as 100pF may improve stability against PCB layout parasitic effects.

Table 2 shows some calculated results based on the compensation method above.

Table 1:

Typical Compensation for Different Output Voltages and Output Capacitors

V _{OUT}	C _{OUT}	R _{COMP}	C _{COMP}	C _{COMP2} ①
2.5V	47μF Ceramic CAP	5.6kΩ	3.3nF	None
3.3V	47μF Ceramic CAP	6.2kΩ	3.3nF	None
5V	47μF Ceramic CAP	8.2kΩ	3.3nF	None
2.5V	470μF/6.3V/30mΩ	39kΩ	22nF	47pF
3.3V	470μF/6.3V/30mΩ	45kΩ	22nF	47pF
5V	470μF/6.3V/30mΩ	51kΩ	22nF	47pF

①: C_{COMP2} is needed for high ESR output capacitor.
C_{COMP2} ≤ 47pF is recommended.

CC Loop Stability

The constant-current control loop is internally compensated over the 750mA-2500mA output range. No additional external compensation is required to stabilize the CC current.

Output Cable Resistance Compensation

To compensate for resistive voltage drop across the charger's output cable, the ACT4513 integrates a simple, user-programmable cable voltage drop compensation using the impedance at the FB pin. Use the curve in Figure 4 to choose the proper feedback resistance values for cable compensation.

STABILITY COMPENSATION CONT'D

R_{FB1} is the high side resistor of voltage divider.

In the case of high R_{FB1} used, the frequency compensation needs to be adjusted correspondingly. As show in Figure 7, adding a capacitor in paralld with R_{FB1} or increasing the compensation capacitance at COMP pin helps the system stability.

Figure 6:

Cable Compensation at Various Resistor Divider Values

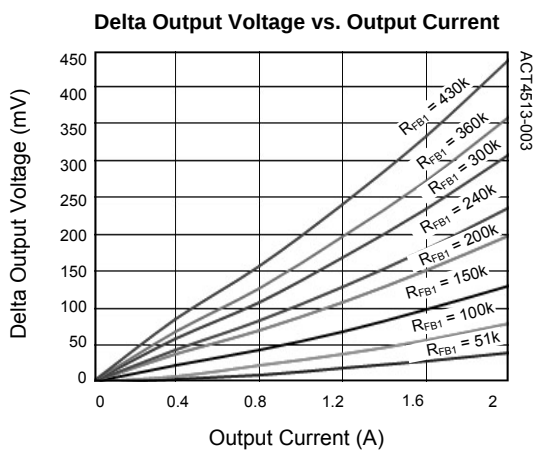
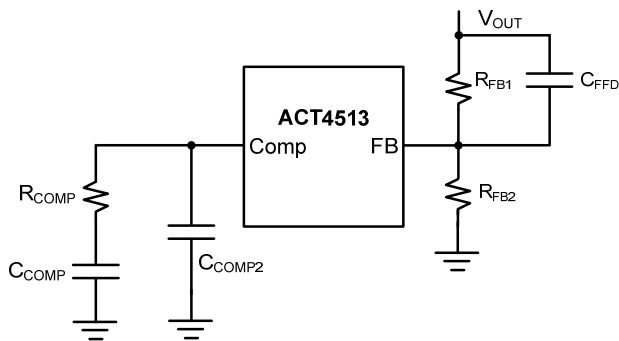


Figure 7:

Frequency Compensation for High R_{FB1}



PC Board Layout Guidance

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the IC.

- 1) Arrange the power components to reduce the AC loop size consisting of C_{IN} , IN pin, SW pin and the schottky diode.
- 2) Place input decoupling ceramic capacitor C_{IN} as

close to IN pin as possible. C_{IN} is connected power GND with vias or short and wide path.

- 3) Return FB, COMP and ISET to signal GND pin, and connect the signal GND to power GND at a single point for best noise immunity.
- 4) Use copper plane for power GND for best heat dissipation and noise immunity.
- 5) Place feedback resistor close to FB pin.
- 6) Use short trace connecting HSB- C_{HSB} -SW loop

Figure 8 shows an example of PCB layout.

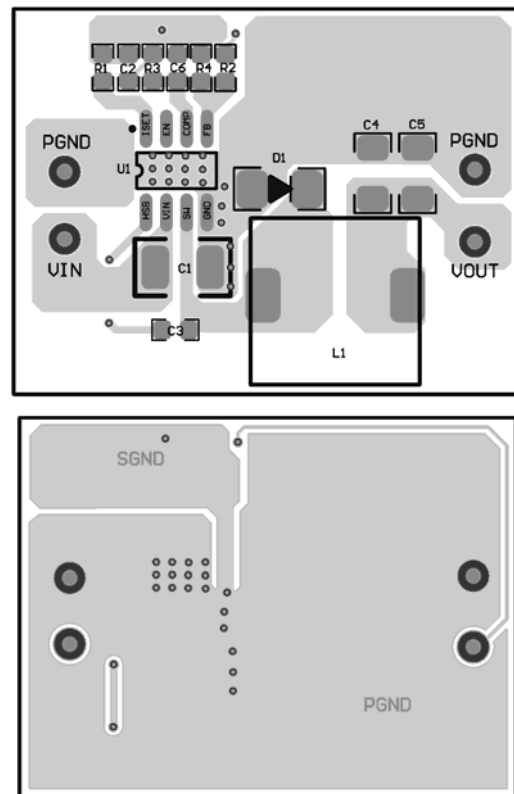


Figure 8: PCB Layout

Figure 9 and Figure 10 give two typical car charger application schematics and associated BOM list.

Figure 10:
Typical Application Circuit for 5V/1.5A Car Charger

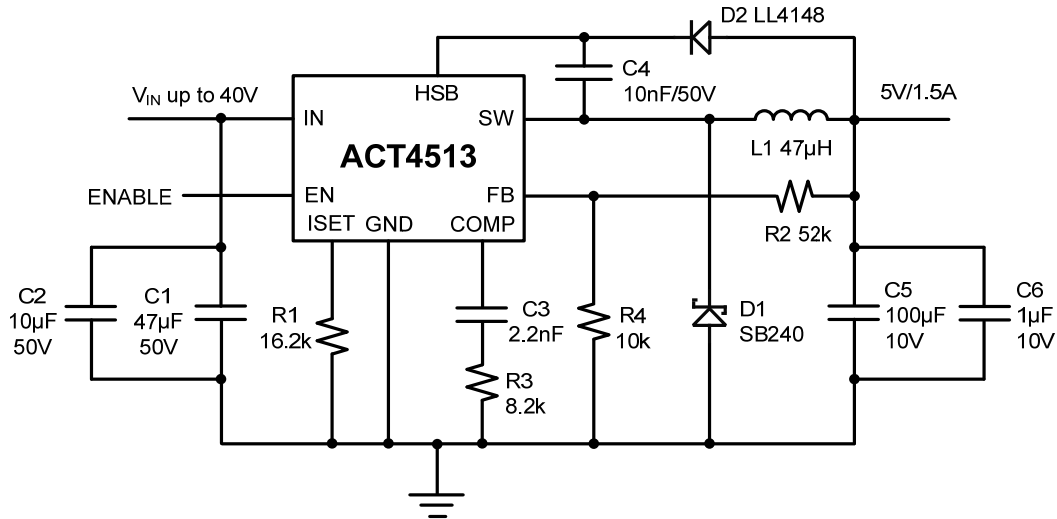
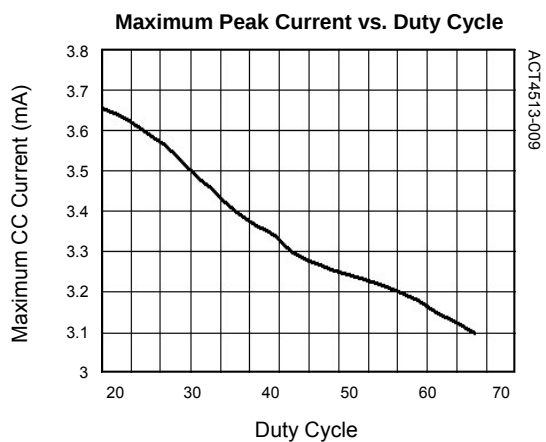
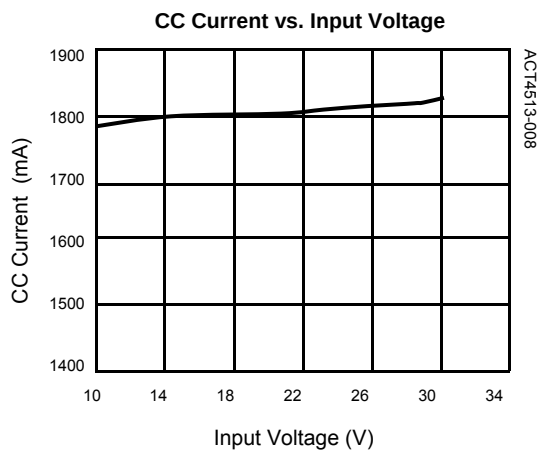
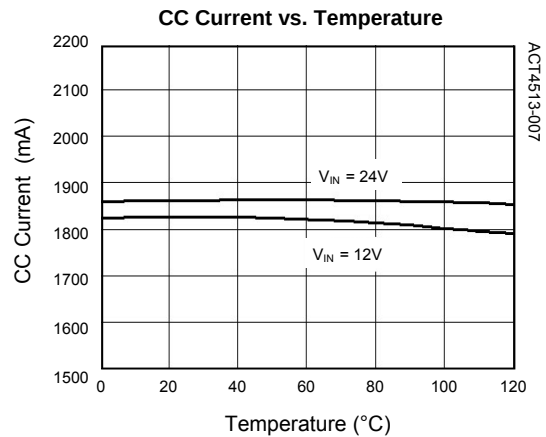
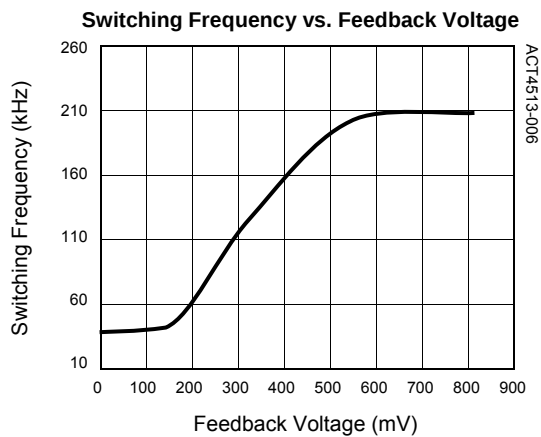
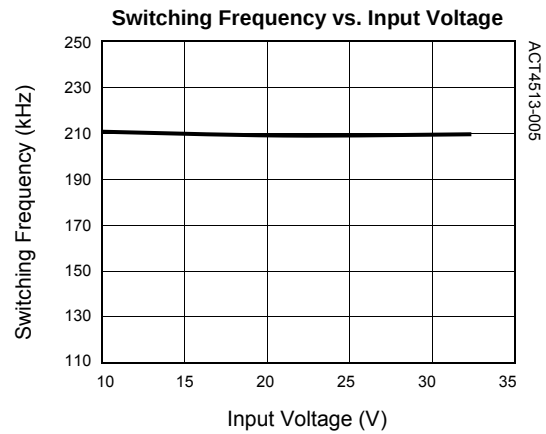
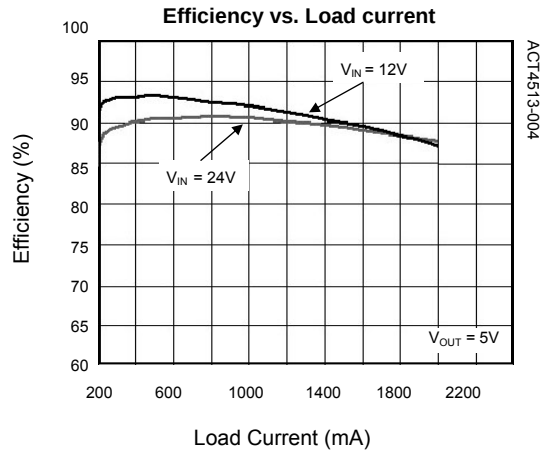


Table 3:
BOM List for 5V/1.5A Car Charger

ITEM	REFERENCE	DESCRIPTION	MANUFACTURER	QTY
1	U1	IC, ACT4513YH, SOP-8EP	Active-Semi	1
2	C1	Capacitor, Electrolytic, 47μF/50V, 6.3x7mm	Murata, TDK	1
3	C2	Capacitor, Ceramic, 10μF/50V, 1210, SMD	Murata, TDK	1
4	C3	Capacitor, Ceramic, 2.2nF/6.3V, 0603, SMD	Murata, TDK	1
5	C4	Capacitor, Ceramic, 10nF/50V, 0603, SMD	Murata, TDK	1
6	C5	Capacitor, Electrolytic, 100μF/10V, 6.3x7mm	Murata, TDK	1
7	C6	Capacitor, Ceramic, 1μF/10V, 0603, SMD	Murata, TDK	1
8	L1	Inductor, 47μH, 2.1A, 20%	Sumida	1
9	D1	Diode, Schottky, 40V/2A, SB240	Diodes	1
10	D2	Diode, 75V/150mA, LL4148	Good-ARK	1
11	R1	Chip Resistor, 16.2kΩ, 0603, 1%	Murata, TDK	1
12	R2	Chip Resistor, 52kΩ, 0603, 1%	Murata, TDK	1
13	R3	Chip Resistor, 8.2kΩ, 0603, 5%	Murata, TDK	1
14	R4	Chip Resistor, 10kΩ, 0603, 1%	Murata, TDK	1

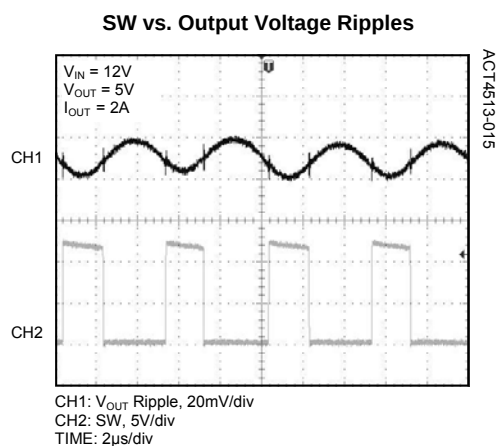
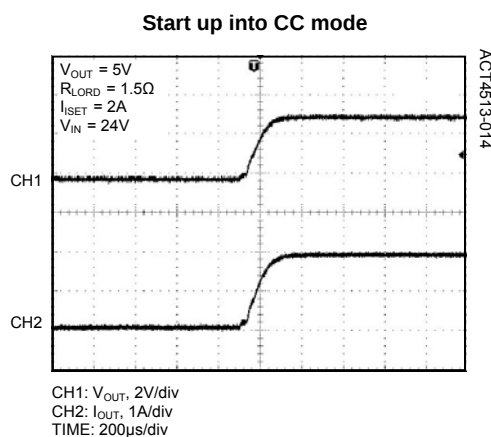
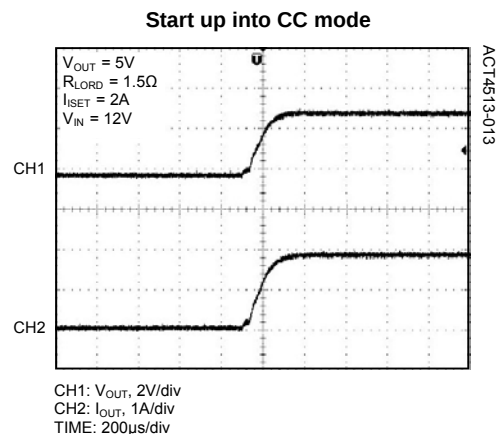
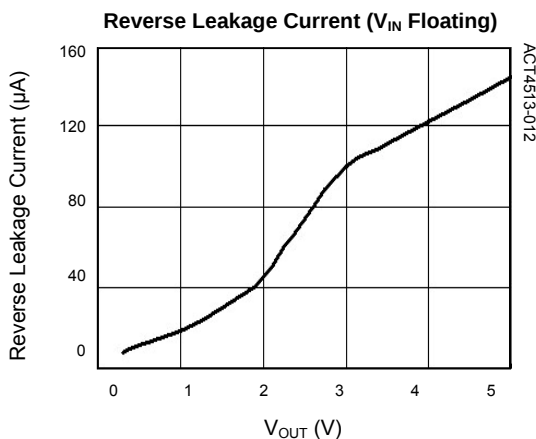
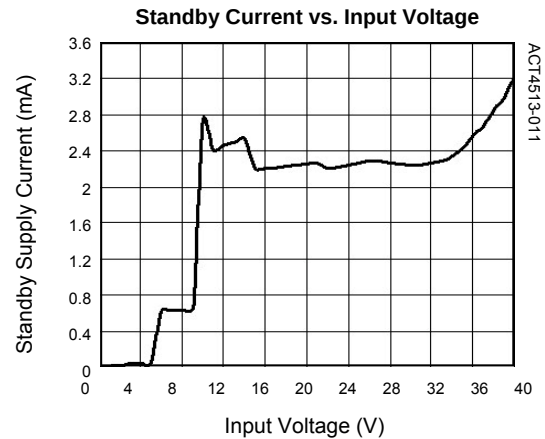
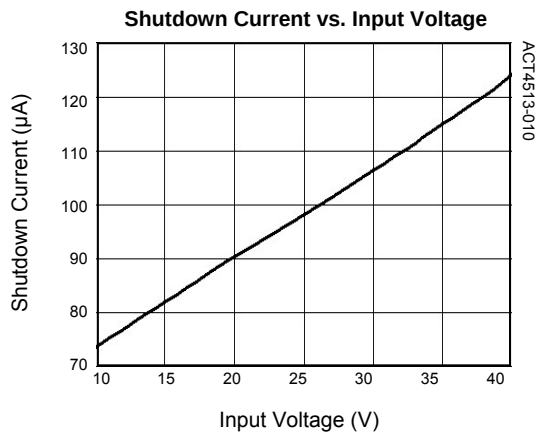
TYPICAL PERFORMANCE CHARACTERISTICS

($L = 33\mu\text{H}$, $C_{\text{IN}} = 10\mu\text{F}$, $C_{\text{OUT}} = 47\mu\text{F}$, $T_a = 25^\circ\text{C}$, $R_{\text{COMP}} = 8.2\text{k}$, $C_{\text{COMP1}} = 2.2\text{nF}$, $C_{\text{COMP2}} = \text{NC}$)



TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

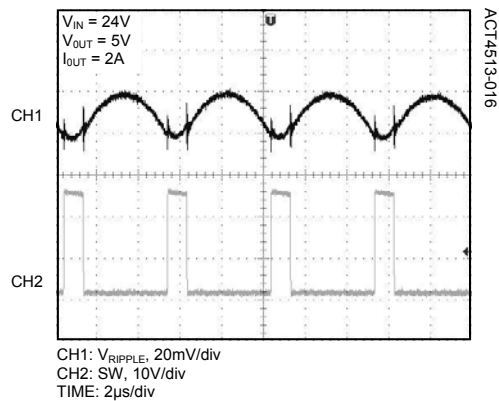
(L = 33 μ H, C_{IN} = 10 μ F, C_{OUT} = 47 μ F, Ta = 25°C, R_{COMP} = 8.2k, C_{COMP1} = 2.2nF, C_{COMP2} = NC)



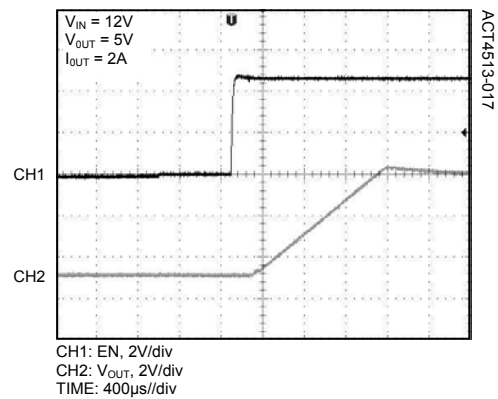
TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

(L = 33 μ H, C_{IN} = 10 μ F, C_{OUT} = 47 μ F, T_a = 25°C, R_{COMP} = 8.2k, C_{COMP1} = 2.2nF, C_{COMP2} = NC)

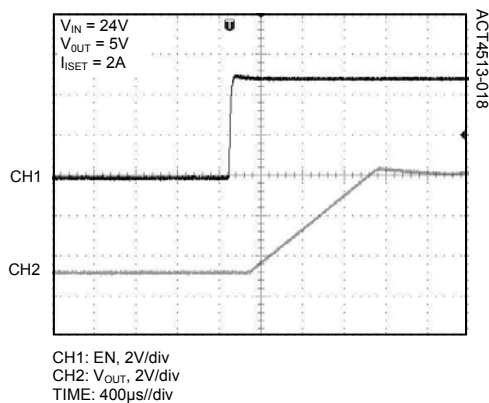
SW vs. Output Voltage Ripple



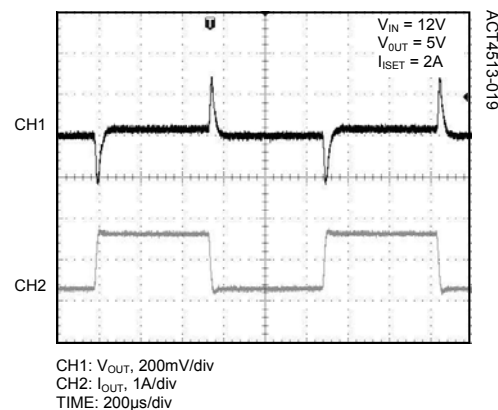
Start up with EN



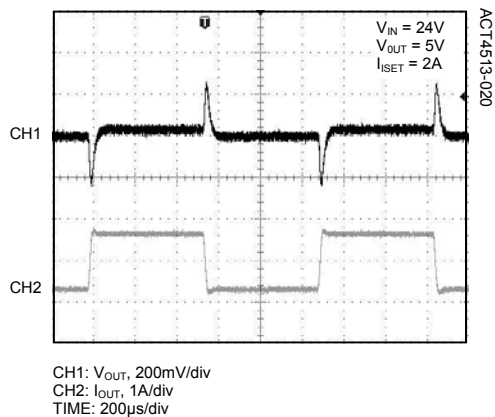
Start up with EN



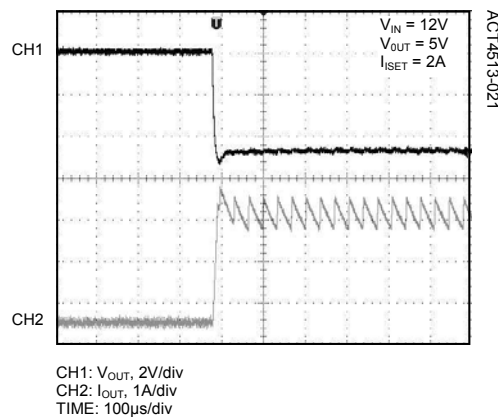
Load Step Waveforms



Load Step Waveforms

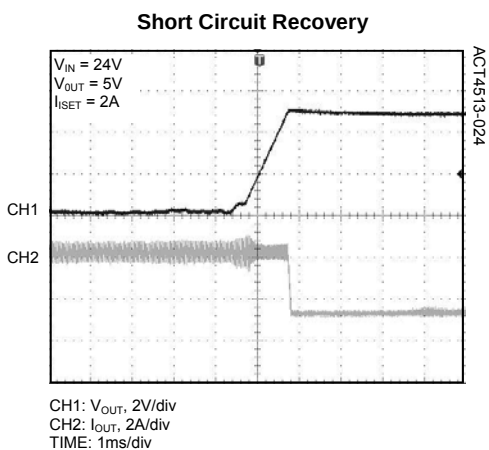
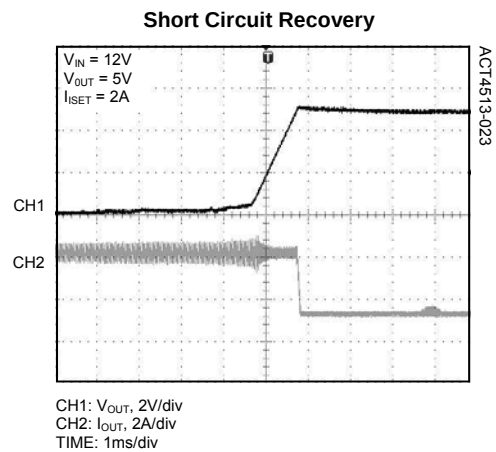
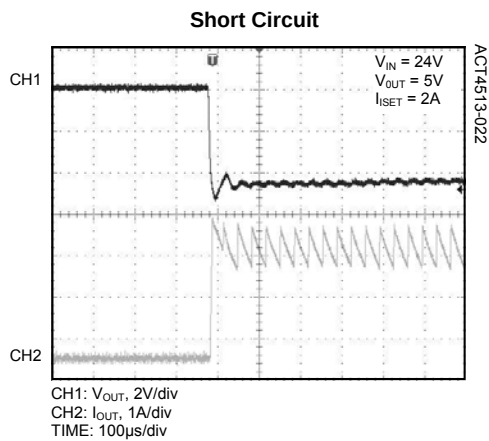


Short Circuit



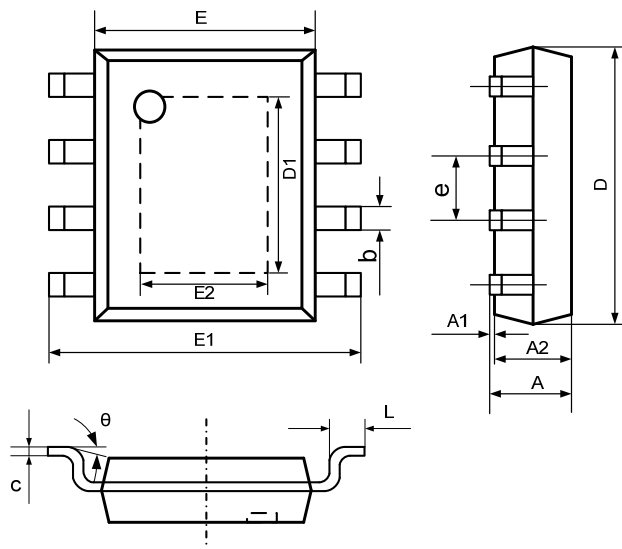
TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

($L = 33\mu\text{H}$, $C_{\text{IN}} = 10\mu\text{F}$, $C_{\text{OUT}} = 47\mu\text{F}$, $T_a = 25^\circ\text{C}$, $R_{\text{COMP}} = 8.2\text{k}$, $C_{\text{COMP1}} = 2.2\text{nF}$, $C_{\text{COMP2}} = \text{NC}$)



PACKAGE OUTLINE

SOP-8EP PACKAGE OUTLINE AND DIMENSIONS



SYMBOL	DIMENSION IN MILLIMETERS		DIMENSION IN INCHES	
	MIN	MAX	MIN	MAX
A	1.350	1.700	0.053	0.067
A1	0.000	0.100	0.000	0.004
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.200
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
E2	2.313	2.513	0.091	0.099
e	1.270 TYP		0.050 TYP	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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